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CLAIMS

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1-14. (Cancelled)

15. (Previously Presented) A process for chemical mechanical polishing of a surface, said process comprising:

- a. subjecting said surface to mechanical abrasion; and
- b. delivering a chemical polishing slurry to said surface;

wherein the step of subjecting said surface to mechanical abrasion is intermittently stopped but the delivery of a chemical polishing slurry to said surface is continuous.

16. (Previously Presented) A process according to claim 15 wherein the mechanical abrasion comprises rotating a polishing pad in contact with said surface.

17. (Previously Presented) A process according to claim 15 wherein the surface comprises a semiconducting layer.

18-21. (Cancelled)